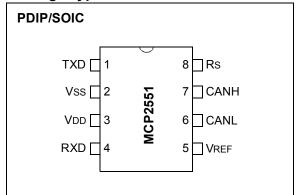


High-Speed CAN Transceiver

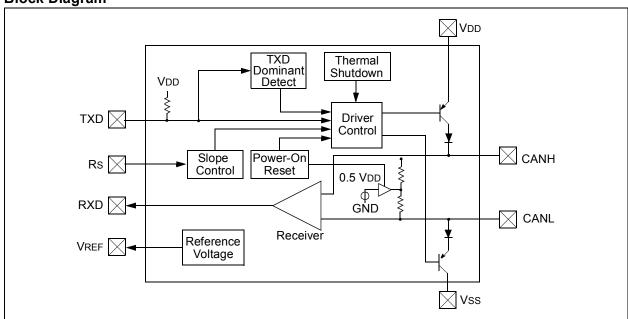
Features

- · Supports 1 Mb/s operation
- Implements ISO-11898 standard physical layer requirements
- · Suitable for 12V and 24V systems
- Externally-controlled slope for reduced RFI emissions
- Detection of ground fault (permanent dominant) on TXD input
- · Power-on reset and voltage brown-out protection
- An unpowered node or brown-out event will not disturb the CAN bus
- · Low current standby operation
- Protection against damage due to short-circuit conditions (positive or negative battery voltage)
- · Protection against high-voltage transients
- · Automatic thermal shutdown protection
- · Up to 112 nodes can be connected
- High noise immunity due to differential bus implementation
- · Temperature ranges:
 - Industrial (I): -40°C to +85°C
 - Extended (E): -40°C to +125°C

Package Types



Block Diagram



1.0 DEVICE OVERVIEW

The MCP2551 is a high-speed CAN, fault-tolerant device that serves as the interface between a CAN protocol controller and the physical bus. The MCP2551 provides differential transmit and receive capability for the CAN protocol controller and is fully compatible with the ISO-11898 standard, including 24V requirements. It will operate at speeds of up to 1 Mb/s.

Typically, each node in a CAN system must have a device to convert the digital signals generated by a CAN controller to signals suitable for transmission over the bus cabling (differential output). It also provides a buffer between the CAN controller and the high-voltage spikes that can be generated on the CAN bus by outside sources (EMI, ESD, electrical transients, etc.).

1.1 Transmitter Function

The CAN bus has two states: Dominant and Recessive. A dominant state occurs when the differential voltage between CANH and CANL is greater than a defined voltage (e.g.,1.2V). A recessive state occurs when the differential voltage is less than a defined voltage (typically 0V). The dominant and recessive states correspond to the low and high state of the TXD input pin, respectively. However, a dominant state initiated by another CAN node will override a recessive state on the CAN bus.

1.1.1 MAXIMUM NUMBER OF NODES

The MCP2551 CAN outputs will drive a minimum load of 45Ω , allowing a maximum of 112 nodes to be connected (given a minimum differential input resistance of 20 k Ω and a nominal termination resistor value of 120Ω).

1.2 Receiver Function

The RXD output pin reflects the differential bus voltage between CANH and CANL. The low and high states of the RXD output pin correspond to the dominant and recessive states of the CAN bus, respectively.

1.3 Internal Protection

CANH and CANL are protected against battery shortcircuits and electrical transients that can occur on the CAN bus. This feature prevents destruction of the transmitter output stage during such a fault condition.

The device is further protected from excessive current loading by thermal shutdown circuitry that disables the output drivers when the junction temperature exceeds a nominal limit of 165°C. All other parts of the chip remain operational and the chip temperature is lowered due to the decreased power dissipation in the transmitter outputs. This protection is essential to protect against bus line short-circuit-induced damage.

1.4 Operating Modes

The Rs pin allows three modes of operation to be selected:

- · High-Speed
- · Slope-Control
- Standby

These modes are summarized in Table 1-1.

When in High-speed or Slope-control mode, the drivers for the CANH and CANL signals are internally regulated to provide controlled symmetry in order to minimize EMI emissions.

Additionally, the slope of the signal transitions on CANH and CANL can be controlled with a resistor connected from pin 8 (Rs) to ground, with the slope proportional to the current output at Rs, further reducing EMI emissions.

1.4.1 HIGH-SPEED

High-speed mode is selected by connecting the Rs pin to Vss. In this mode, the transmitter output drivers have fast output rise and fall times to support high-speed CAN bus rates.

1.4.2 SLOPE-CONTROL

Slope-control mode further reduces EMI by limiting the rise and fall times of CANH and CANL. The slope, or slew rate (SR), is controlled by connecting an external resistor (REXT) between Rs and Vol (usually ground). The slope is proportional to the current output at the Rs pin. Since the current is primarily determined by the slope-control resistance value REXT, a certain slew rate is achieved by applying a respective resistance. Figure 1-1 illustrates typical slew rate values as a function of the slope-control resistance value.

1.4.3 STANDBY MODE

The device may be placed in standby or "SLEEP" mode by applying a high-level to Rs. In SLEEP mode, the transmitter is switched off and the receiver operates at a lower current. The receive pin on the controller side (RXD) is still functional but will operate at a slower rate. The attached microcontroller can monitor RXD for CAN bus activity and place the transceiver into normal operation via the Rs pin (at higher bus rates, the first CAN message may be lost).

TABLE 1-1: MODES OF OPERATION

Mode	Current at R _s Pin	Resulting Voltage at Rs Pin					
Standby	-lrs < 10 μA	VRS > 0.75 VDD					
Slope-control 10 μ A < -IRS < 200 μ A 0.		0.4 VDD < VRS < 0.6 VDD					
High-speed	-IRS < 610 μA	0 < VRS < 0.3VDD					

TABLE 1-2: TRANSCEIVER TRUTH TABLE

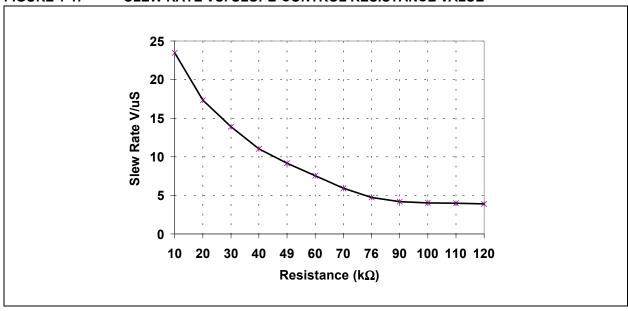
VDD	VRS	TXD	CANH	CANL	Bus State ⁽¹⁾	RxD ⁽¹⁾
4.5V ≤ VDD ≤ 5.5V	VRS < 0.75 VDD	0	HIGH	LOW	Dominant	0
		1 or floating	Not Driven	Not Driven	Recessive	1
	VRS > 0.75 VDD	X	Not Driven	Not Driven	Recessive	1
VPOR < VDD < 4.5V	VRS < 0.75 VDD	0	HIGH	LOW	Dominant	0
(See Note 3)		1 or floating	Not Driven	Not Driven	Recessive	1
	VRS > 0.75 VDD	X	Not Driven	Not Driven	Recessive	1
0 < VDD < VPOR	X	Х	Not Driven/	Not Driven/	High Impedance	Х
			No Load	No Load		

Note 1: If another bus node is transmitting a dominant bit on the CAN bus, then RXD is a logic '0'.

2: X = "don't care".

3: Device drivers will function, although outputs are not ensured to meet the ISO-11898 specification.

FIGURE 1-1: SLEW RATE VS. SLOPE-CONTROL RESISTANCE VALUE



1.5 TXD Permanent Dominant Detection

If the MCP2551 detects an extended low state on the TXD input, it will disable the CANH and CANL output drivers in order to prevent the corruption of data on the CAN bus. The drivers are disabled if TXD is low for more than 1.25 ms (minimum). This implies a maximum bit time of 62.5 μs (16 kb/s bus rate), allowing up to 20 consecutive transmitted dominant bits during a multiple bit error and error frame scenario. The drivers remain disabled as long as TXD remains low. A rising edge on TXD will reset the timer logic and enable the CANH and CANL output drivers.

1.6 Power-on Reset

When the device is powered on, CANH and CANL remain in a high-impedance state until VDD reaches the voltage-level VPORH. In addition, CANH and CANL will remain in a high-impedance state if TXD is low when VDD reaches VPORH. CANH and CANL will become active only after TXD is asserted high. Once powered on, CANH and CANL will enter a high-impedance state if the voltage level at VDD falls below VPORL, providing voltage brown-out protection during normal operation.

1.7 Pin Descriptions

The 8-pin pinout is listed in Table 1-3.

TABLE 1-3: MCP2551 PINOUT

Pin Number	Pin Name	Pin Function			
1	TXD	Transmit Data Input			
2	Vss	Ground			
3	Vdd	Supply Voltage			
4	RXD	Receive Data Output			
5	VREF	Reference Output Voltage			
6	CANL	CAN Low-Level Voltage I/O			
7	CANH	CAN High-Level Voltage I/O			
8	Rs	Slope-Control Input			

1.7.1 TRANSMITTER DATA INPUT (TXD)

TXD is a TTL-compatible input pin. The data on this pin is driven out on the CANH and CANL differential output pins. It is usually connected to the transmitter data output of the CAN controller device. When TXD is low, CANH and CANL are in the dominant state. When TXD is high, CANH and CANL are in the recessive state, provided that another CAN node is not driving the CAN bus with a dominant state. TXD has an internal pull-up resistor (nominal 25 k Ω to VDD).

1.7.2 GROUND SUPPLY (Vss)

Ground supply pin.

1.7.3 SUPPLY VOLTAGE (VDD)

Positive supply voltage pin.

1.7.4 RECEIVER DATA OUTPUT (RXD)

RXD is a CMOS-compatible output that drives high or low depending on the differential signals on the CANH and CANL pins and is usually connected to the receiver data input of the CAN controller device. RXD is high when the CAN bus is recessive and low in the dominant state.

1.7.5 REFERENCE VOLTAGE (VREF)

Reference Voltage Output (Defined as VDD/2).

1.7.6 CAN LOW (CANL)

The CANL output drives the low side of the CAN differential bus. This pin is also tied internally to the receive input comparator.

1.7.7 CAN HIGH (CANH)

The CANH output drives the high-side of the CAN differential bus. This pin is also tied internally to the receive input comparator.

1.7.8 SLOPE RESISTOR INPUT (Rs)

The Rs pin is used to select High-speed, Slope-control or Standby modes via an external biasing resistor.

2.0 ELECTRICAL CHARACTERISTICS

2.1 Terms and Definitions

A number of terms are defined in ISO-11898 that are used to describe the electrical characteristics of a CAN transceiver device. These terms and definitions are summarized in this section.

2.1.1 BUS VOLTAGE

VCANL and VCANH denote the voltages of the bus line wires CANL and CANH relative to ground of each individual CAN node.

2.1.2 COMMON MODE BUS VOLTAGE RANGE

Boundary voltage levels of VCANL and VCANH with respect to ground, for which proper operation will occur, if up to the maximum number of CAN nodes are connected to the bus.

2.1.3 DIFFERENTIAL INTERNAL CAPACITANCE, CDIFF (OF A CAN NODE)

Capacitance seen between CANL and CANH during the recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

2.1.4 DIFFERENTIAL INTERNAL RESISTANCE, RDIFF (OF A CAN NODE)

Resistance seen between CANL and CANH during the recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

2.1.5 DIFFERENTIAL VOLTAGE, VDIFF (OF CAN BUS)

Differential voltage of the two-wire CAN bus, value VDIFF = VCANH - VCANL.

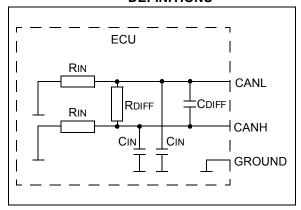
2.1.6 INTERNAL CAPACITANCE, CIN (OF A CAN NODE)

Capacitance seen between CANL (or CANH) and ground during the recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

2.1.7 INTERNAL RESISTANCE, RIN (OF A CAN NODE)

Resistance seen between CANL (or CANH) and ground during the recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

FIGURE 2-1: PHYSICAL LAYER DEFINITIONS



Absolute Maximum Ratings†

VDD	7.0V
DC Voltage at TXD, RXD, VREF and Vs	0.3V to VDD + 0.3V
DC Voltage at CANH, CANL (Note 1)	42V to +42V
Transient Voltage on Pins 6 and 7 (Note 2)	250V to +250V
Storage temperature	55°C to +150°C
Operating ambient temperature	40°C to +125°C
Virtual Junction Temperature, TvJ (Note 3)	40°C to +150°C
Soldering temperature of leads (10 seconds)	+300°C
ESD protection on CANH and CANL pins (Note 4)	6 kV
ESD protection on all other pins (Note 4)	4 kV
Note 1: Short-circuit applied when TXD is high and low.	
2: In accordance with ISO 7637	

- 2: In accordance with ISO-7637.
- 3: In accordance with IEC 60747-1.
- 4: Classification A: Human Body Model.

† NOTICE: Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2.2 DC Characteristics

DC Speci	fications		Industrial (I	,	°C to +8	85°C VDD = 4.5V to 5.5V 125°C VDD = 4.5V to 5.5V
Param No.	Sym	Characteristic	Min	Max	Units	Conditions
Supply						
D1	IDD	Supply Current	_	75	mA	Dominant; VTXD = 0.8V; VDD
D2				10	mA	Recessive; VTXD = +2V; Rs = 47 k Ω
D3			_	365	μA	$-40^{\circ}\text{C} \le \text{T}_{\text{AMB}} \le +85^{\circ}\text{C},$ Standby; (Note 2)
			_	465	μA	-40 °C \leq T _{AMB} \leq +125°C, Standby; (Note 2)
D4	VPORH	High-level of the power-on reset comparator	3.8	4.3	V	CANH, CANL outputs are active when VDD > VPORH
D5	VPORL	Low-level of the power-on reset comparator	3.4	4.0	V	CANH, CANL outputs are not active when VDD < VPORL
D6	VPORD	Hysteresis of power-on reset comparator	0.3	0.8	V	Note 1
Bus Line	(CANH; CANL) Tra	ansmitter				
D7	$VCANH_{(r)};VCANL_{(r)}$	CANH, CANL Recessive bus voltage	2.0	3.0	V	VTXD = VDD; no load.
D8	IO(CANH)(reces) IO(CANL)(reces)	Recessive output current	-2	+2	mA	-2V < V(CAHL,CANH) < +7V, 0V <vdd 5.5v<="" <="" td=""></vdd>
D9			-10	+10	mA	-5V < V(CANL,CANH) < +40V, 0V <vdd 5.5v<="" <="" td=""></vdd>
D10	Vo(canh)	CANH dominant output voltage	2.75	4.5	V	VTXD = 0.8V
D11	Vo(canl)	CANL dominant output voltage	0.5	2.25	V	VTXD = 0.8V
D12	VDIFF(r)(o)	Recessive differential output voltage	-500	+50	mV	VTXD = 2V; no load
D13	VDIFF(d)(o)	Dominant differential output voltage	1.5	3.0	V	$V_{TXD} = 0.8V; V_{DD} = 5V$ $40Ω < R_L < 60Ω$ (Note 2)
D14	Io(SC)(canh)	CANH short-circuit output current	_	-200	mA	VCANH = -5V
D15			1	-100 (typical)	mA	VCANH = -40V, +40V. (Note 1)
D16	Io(SC)(CANL)I	CANL short-circuit output current	-	200	mA	VCANL = -40V, +40V. (Note 1)
Bus Line	(CANH; CANL) Re	ceiver: [TXD = 2V; pins 6 and 7 ex	ternally dri	ven]		
D17	VDIFF(r)(i)	Recessive differential input voltage	-1.0	+0.5	V	-2V < V(CANL, CANH) < +7V (Note 3)
			-1.0	+0.4	V	-12V < V(CANL, CANH) < +12V (Note 3)
D18	VDIFF(d)(i)	Dominant differential input voltage	0.9	5.0	V	-2V < V(CANL, CANH) < +7V (Note 3)
			1.0	5.0	V	-12V < V(CANL, CANH) < +12V (Note 3)
D19	VDIFF(h)(i)	Differential input hysteresis	100	200	mV	see Figure 2-3. (Note 1)
D20	Rin	CANH, CANL common-mode input resistance	5	50	kΩ	
D21	Rın(d)	Deviation between CANH and CANL common-mode input resistance	-3	+3	%	VCANH = VCANL

Note 1: This parameter is periodically sampled and not 100% tested.

^{2:} ITXD = IRXD = IVREF = 0 mA; 0V < VCANL < VDD; 0V < VCANH < VDD; VRS = VDD

^{3:} This is valid for the receiver in all modes; High-speed, Slope-control and Standby.

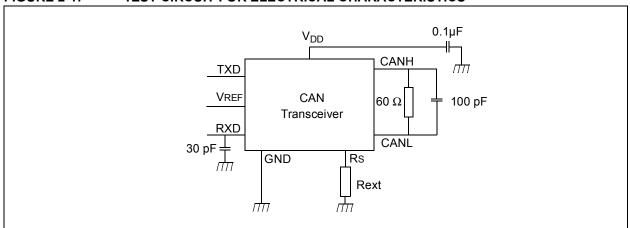
2.2 DC Characteristics (Continued)

DC Specifications (Continued)			Electrical Characteristics: Industrial (I): TAMB = -40°C to +85°C VDD = 4.5V to 5.5V Extended (E):TAMB = -40°C to +125°C VDD = 4.5V to 5.5V				
Param No.	Sym	Characteristic	Min	Max	Units	Conditions	
Bus Line (CANH; CANL) F	Receiver: [TXD = 2V; pins 6 and 7 e	xternally driv	/en]			
D22	Rdiff	Differential input resistance	20	100	kΩ		
D24	lLi	CANH, CANL input leakage current	_	150	μА	VDD < VPOR; VCANH = VCANL = +5V	
Transmitte	er Data Input (T	(D)					
D25	Vih	High-level input voltage	2.0	Vdd	V	Output recessive	
D26	VIL	Low-level input voltage	Vss	+0.8	V	Output dominant	
D27	lін	High-level input current	-1	+1	μΑ	VTXD = VDD	
D28	lıL	Low-level input current	-100	-400	μA	VTXD = 0V	
Receiver I	Data Output (RX	D)	•	•	•	•	
D31	Voн	High-level output voltage	0.7 VDD		V	Iон = 8 mA	
D32	Vol	Low-level output voltage	_	0.8	V	IOL = 8 mA	
Voltage Re	eference Output	(VREF)					
D33	VREF	Reference output voltage	0.45 VDD	0.55 VDD	V	-50 μA < IVREF < 50 μA	
Standby/S	lope-Control (R	s pin)			_		
D34	Vstb	Input voltage for standby mode	0.75 VDD	-	V		
D35	ISLOPE	Slope-control mode current	-10	-200	μΑ		
D36	VSLOPE	Slope-control mode voltage	0.4 VDD	0.6 Vdd	V		
Thermal S	hutdown						
D37	$TJ_{(sd)}$	Shutdown junction temperature	155	180	°C	Note 1	
D38	TJ _(h)	Shutdown temperature hysteresis	20	30	°C	-12V < V(CANL, CANH) < +12V (Note 3)	

Note 1: This parameter is periodically sampled and not 100% tested.

- 2: ITXD = IRXD = IVREF = 0 mA; 0V < VCANL < VDD; 0V < VCANH < VDD; VRS = VDD
- **3:** This is valid for the receiver in all modes; High-speed, Slope-control and Standby.

FIGURE 2-1: TEST CIRCUIT FOR ELECTRICAL CHARACTERISTICS



Note: Rs may be connected to VDD or GND via a load resistor depending on desired operating mode as described in Section 1.7.8, "Slope Resistor Input (Rs)".

FIGURE 2-2: TEST CIRCUIT FOR AUTOMOTIVE TRANSIENTS

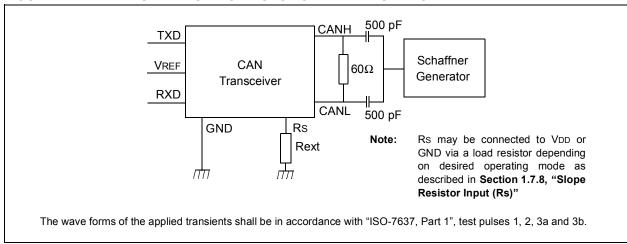
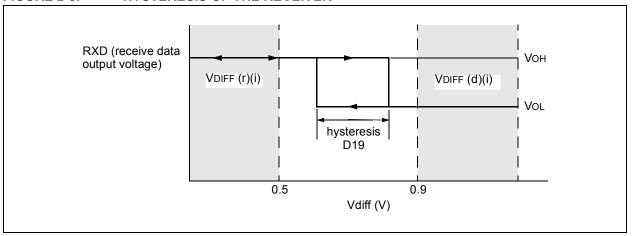


FIGURE 2-3: HYSTERESIS OF THE RECEIVER



2.3 AC Characteristics

AC Specifications			Electrical Characteristics: Industrial (I): TAMB = -40°C to +85°C VDD = 4.5V to 5.5V Extended (E): TAMB = -40°C to +125°C VDD = 4.5V to 5.5V				
Param No.	Sym	Characteristic	Min	Max	Units	Conditions	
1	tвіт	Bit time	1	62.5	μs	VRS = 0V	
2	fвіт	Bit frequency	16	1000	kHz	VRS = 0V	
3	TtxL2bus(d)	Delay TXD to bus active	_	70	ns	-40°C ≤ TAMB ≤ +125°C, VRS = 0V	
4	TtxH2bus(r)	Delay TXD to bus inactive	_	125	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +85^{\circ}\text{C},$ VRS = 0V	
			_	170	ns	-40°C ≤ TAMB ≤ +125°C, VRS = 0V	
5	TtxL2rx(d)	Delay TXD to receive active	_	130	ns	-40°C ≤ TAMB ≤ +125°C, VRS = 0V	
			_	250	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ Rs = 47 k Ω	
6	TtxH2rx(r)	Delay TXD to receiver inactive	_	175	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +85^{\circ}\text{C},$ VRS = 0V	
			_	225	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +85^{\circ}\text{C},$ Rs = 47 k Ω	
			_	235	ns	-40°C ≤ TAMB ≤ +125°C, VRS = 0V	
			_	400	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ Rs = 47 k Ω	
7	SR	CANH, CANL slew rate	5.5	8.5	V/µs	Refer to Figure 1-1; Rs = 47 k Ω , (Note 1)	
10	twake	Wake-up time from standby (Rs pin)	_	5	μs	see Figure 2-5	
11	TbusD2rx(s)	Bus dominant to RXD Low (Standby mode)	_	550	ns	VRS = +4V; (see Figure 2-2)	
12	CIN(CANH) CIN(CANL)	CANH; CANL input capacitance	_	20 (typical)	pF	1 Mbit/s data rate; VTXD = VDD, (Note 1)	
13	CDIFF	Differential input capacitance	_	10 (typical)	pF	1 Mbit/s data rate (Note 1)	
14	TtxL2busZ	TX Permanent Dominant Timer Disable Time	1.25	4	ms		
15	TtxR2pdt(res)	TX Permanent Dominant Timer Reset Time	_	1	μs	Rising edge on TXD while device is in permanent dominant state	

Note 1: This parameter is periodically sampled and not 100% tested.

2.4 Timing Diagrams and Specifications

FIGURE 2-4: TIMING DIAGRAM FOR AC CHARACTERISTICS

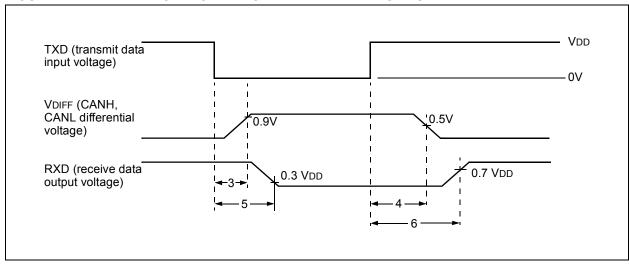


FIGURE 2-5: TIMING DIAGRAM FOR WAKE-UP FROM STANDBY

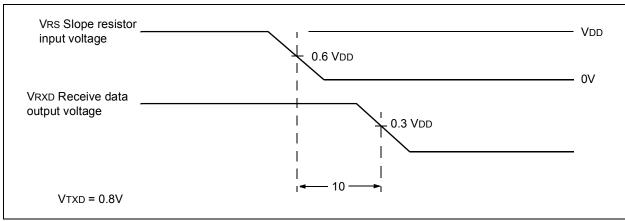
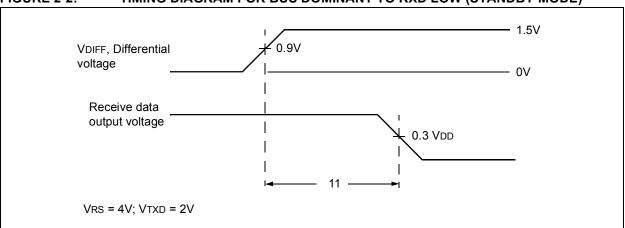


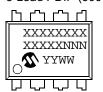
FIGURE 2-2: TIMING DIAGRAM FOR BUS DOMINANT TO RXD LOW (STANDBY MODE)

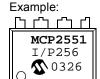


3.0 PACKAGING INFORMATION

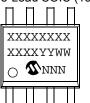
3.1 Package Marking Information

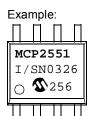












Legend: XX...X Customer specific information*

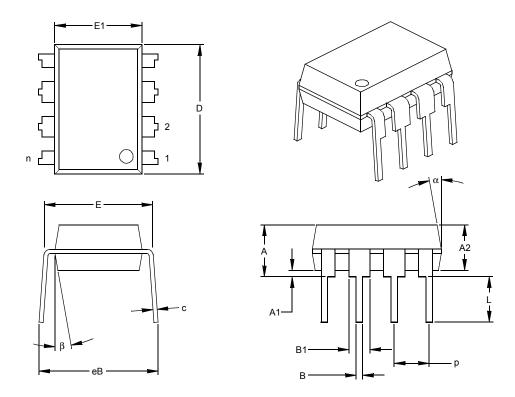
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard marking consists of Microchip part number, year code, week code, traceability code (facility code, mask rev#, and assembly code). For marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.

8-Lead Plastic Dual In-line (P) - 300 mil (PDIP)



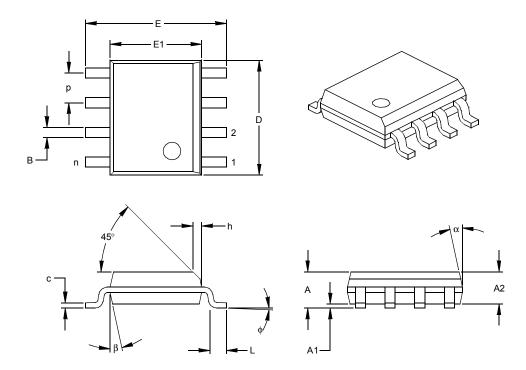
Units		INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eВ	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001
Drawing No. C04-018

^{*} Controlling Parameter § Significant Characteristic

8-Lead Plastic Small Outline (SN) - Narrow, 150 mil (SOIC)



	Units	ts INCHES*		MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.050			1.27	
Overall Height	Α	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	ф	0	4	8	0	4	8
Lead Thickness	С	.008	.009	.010	0.20	0.23	0.25
Lead Width	В	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side.
JEDEC Equivalent: MS-012
Drawing No. C04-057

^{*} Controlling Parameter § Significant Characteristic

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>X</u>	Ex	amples:	
Device	Temperature Package	a)	MCP2551-I/P:	Industrial temperature, PDIP package.
	Range	b)	MCP2551-E/P:	Extended temperature, PDIP package.
Device:	MCP2551= High-Speed CAN Transceiver	c)	MCP2551-I/SN:	Industrial temperature, SOIC package.
Temperature Range:	I = -40°C to +85°C E = -40°C to +125°C	d)	MCP2551T-I/SN:	Tape and Reel, Industrial Temperature, SOIC package.
Package:	P = Plastic DIP (300 mil Body) 8-lead SN = Plastic SOIC (150 mil Body) 8-lead	e)	MCP2551T-E/SN:	Tape and Reel, Extended Temperature, SOIC package.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- 1. Your local Microchip sales office
- 2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
- 3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
 Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, Keeloq, MPLAB, PIC, PICmicro, PICSTART, PRO MATE and PowerSmart are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

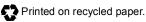
AmpLab, FilterLab, microID, MXDEV, MXLAB, PICMASTER, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

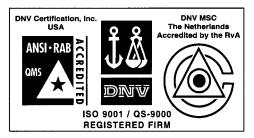
Application Maestro, dsPICDEM, dsPICDEM.net, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, microPort, Migratable Memory, MPASM, MPLIB, MPLINK, MPSIM, PICkit, PICDEM, PICDEM.net, PowerCal, PowerInfo, PowerMate, PowerTool, rfLAB, rfPIC, Select Mode, SmartSensor, SmartShunt, SmartTel and Total Endurance are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2003, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.





Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999 and Mountain View, California in March 2002. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, non-volatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200

Fax: 480-792-7277 Technical Support: 480-792-7627 Web Address: http://www.microchip.com

Atlanta

3780 Mansell Road, Suite 130 Alpharetta, GA 30022 Tel: 770-640-0034 Fax: 770-640-0307

Boston

2 Lan Drive, Suite 120 Westford, MA 01886 Tel: 978-692-3848 Fax: 978-692-3821

Chicago

333 Pierce Road, Suite 180 Itasca, IL 60143 Tel: 630-285-0071 Fax: 630-285-0075

4570 Westgrove Drive, Suite 160 Addison, TX 75001 Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Tri-Atria Office Building 32255 Northwestern Highway, Suite 190 Farmington Hills, MI 48334

Tel: 248-538-2250 Fax: 248-538-2260 Kokomo

2767 S. Albright Road Kokomo, IN 46902 Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

18201 Von Karman, Suite 1090 Irvine, CA 92612 Tel: 949-263-1888 Fax: 949-263-1338

Phoenix

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7966 Fax: 480-792-4338

San Jose

2107 North First Street, Suite 590 San Jose, CA 95131 Tel: 408-436-7950

Fax: 408-436-7955 Toronto

6285 Northam Drive, Suite 108

Mississauga, Ontario L4V 1X5, Canada Tel: 905-673-0699

Fax: 905-673-6509

ASIA/PACIFIC

Australia

Suite 22, 41 Rawson Street Epping 2121, NSW Australia Tel: 61-2-9868-6733

Fax: 61-2-9868-6755 China - Beijing

Unit 915

Bei Hai Wan Tai Bldg. No. 6 Chaoyangmen Beidajie Beijing, 100027, No. China Tel: 86-10-85282100 Fax: 86-10-85282104 China - Chengdu

Rm. 2401-2402, 24th Floor, Ming Xing Financial Tower No. 88 TIDU Street Chengdu 610016, China Tel: 86-28-86766200 Fax: 86-28-86766599

China - Fuzhou

Unit 28F. World Trade Plaza No. 71 Wusi Road Fuzhou 350001, China Tel: 86-591-7503506 Fax: 86-591-7503521

China - Hong Kong SAR

Unit 901-6, Tower 2, Metroplaza 223 Hing Fong Road Kwai Fong, N.T., Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Shanghai Room 701, Bldg. B Far East International Plaza No. 317 Xian Xia Road Shanghai, 200051 Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen

Rm. 1812, 18/F, Building A, United Plaza No. 5022 Binhe Road, Futian District Shenzhen 518033, China

Tel: 86-755-82901380 Fax: 86-755-8295-1393

China - Shunde

Room 401, Hongjian Building No. 2 Fengxiangnan Road, Ronggui Town Shunde City, Guangdong 528303, China Tel: 86-765-8395507 Fax: 86-765-8395571

China - Qingdao

Rm. B505A, Fullhope Plaza, No. 12 Hong Kong Central Rd. Qingdao 266071, China Tel: 86-532-5027355 Fax: 86-532-5027205

India

Divyasree Chambers 1 Floor, Wing A (A3/A4) No. 11, O'Shaugnessey Road Bangalore, 560 025, India Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Benex S-1 6F 3-18-20, Shinyokohama Kohoku-Ku, Yokohama-shi Kanagawa, 222-0033, Japan Tel: 81-45-471- 6166 Fax: 81-45-471-6122 Korea

168-1, Youngbo Bldg. 3 Floor Samsung-Dong, Kangnam-Ku Seoul, Korea 135-882 Tel: 82-2-554-7200 Fax: 82-2-558-5932 or

82-2-558-5934

Singapore

200 Middle Road #07-02 Prime Centre Singapore, 188980

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan

Kaohsiung Branch 30F - 1 No. 8 Min Chuan 2nd Road Kaohsiung 806, Taiwan Tel: 886-7-536-4818 Fax: 886-7-536-4803

Taiwan

Taiwan Branch 11F-3, No. 207 Tung Hua North Road Taipei, 105, Taiwan

Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

FUROPE

Austria

Durisolstrasse 2 A-4600 Wels Austria

Tel: 43-7242-2244-399

Fax: 43-7242-2244-393

Denmark

Regus Business Centre Lautrup hoj 1-3 Ballerup DK-2750 Denmark

Tel: 45-4420-9895 Fax: 45-4420-9910

France

Parc d'Activite du Moulin de Massy 43 Rue du Saule Trapu Batiment A - Ier Etage 91300 Massy, France Tel: 33-1-69-53-63-20

Germany

Steinheilstrasse 10 D-85737 Ismaning, Germany Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy

Via Quasimodo, 12 20025 Legnano (MI) Milan, Italy Tel: 39-0331-742611 Fax: 39-0331-466781

Fax: 33-1-69-30-90-79

Netherlands

P. A. De Biesbosch 14 NL-5152 SC Drunen, Netherlands Tel: 31-416-690399

Fax: 31-416-690340 **United Kingdom**

505 Eskdale Road Winnersh Triangle Wokingham

Berkshire, England RG41 5TU Tel: 44-118-921-5869 Fax: 44-118-921-5820

07/28/03

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.